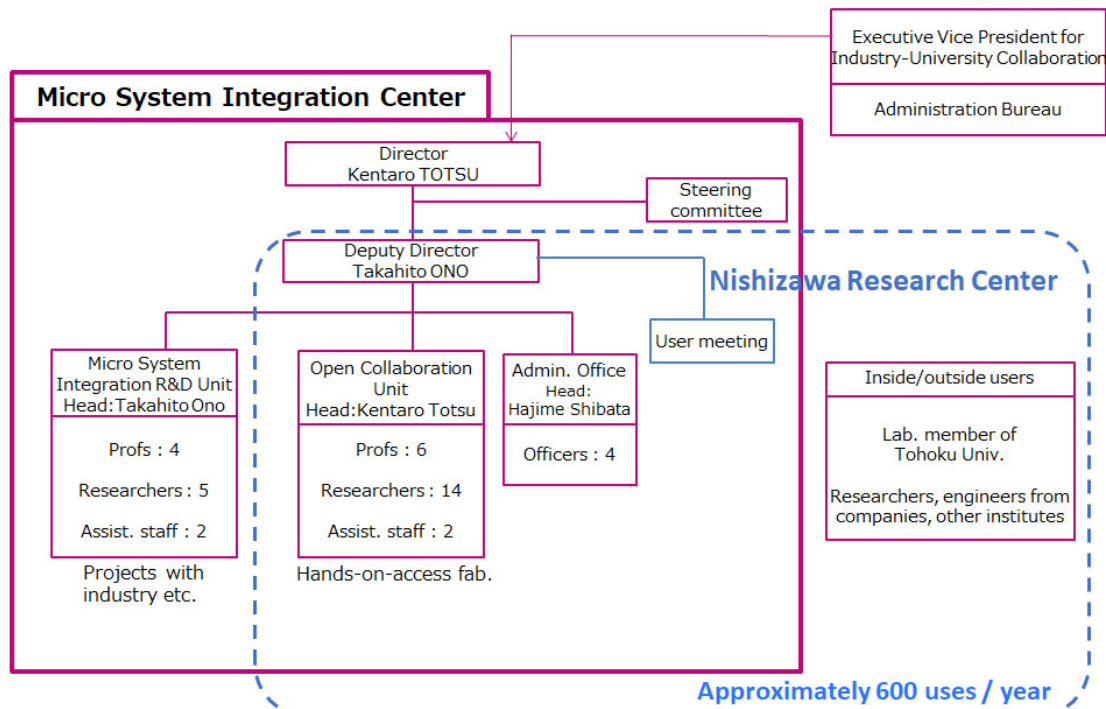
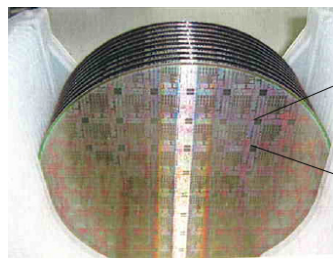


As of April 2025



MEMS prototyping (20mm□wafer)



Shared wafer (16 companies)

Company A	Company B
Project C	Project D



Partnership between FhG and Sendai



MicroNanomachining Research & Education Center (MNC)

Micro System Integration Center (μ SIC)

AIIST Research Center for Ubiquitous MEMS and Micro Eng. (UMEMSME)



MEMS Core Co. Ltd.